

[54] **HEAT-SINK COVER FOR LEADLESS ELECTRONIC CHIP-CARRIER SOCKETS**

[75] **Inventor: Alfred F. McCarthy, Belmont, N.H.**

[73] **Assignee: Aavid Engineering, Inc., Laconia, N.H.**

[**] **Term: 14 Years**

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[52] **U.S. Cl. D13/23**

[58] **Field of Search D13/23; 174/16 HS; 361/386, 388; 357/81; 165/80.1, 80.2, 80.3**

[56] **References Cited**

U.S. PATENT DOCUMENTS

- D. 285,194 8/1986 McCarthy D13/23
- D. 285,302 8/1986 McCarthy D13/23

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Primary Examiner—Susan J. Lucas

[57] **CLAIM**

The ornamental design for a heat-sink cover for leadless electronic chip-carrier sockets, as shown and described.

DESCRIPTION

FIG. 1 is a perspective view of a heat sink cover for leadless electronic chip carrier sockets showing my new design;

FIG. 2 is a side elevational view thereof as seen from the left of FIG. 1, the opposite side being a mirror image;

FIG. 3 is a side elevational view thereof as seen from the right of FIG. 1, the opposite side being a mirror image;

FIG. 4 is a top plan view thereof; and

FIG. 5 is a bottom plan view thereof.

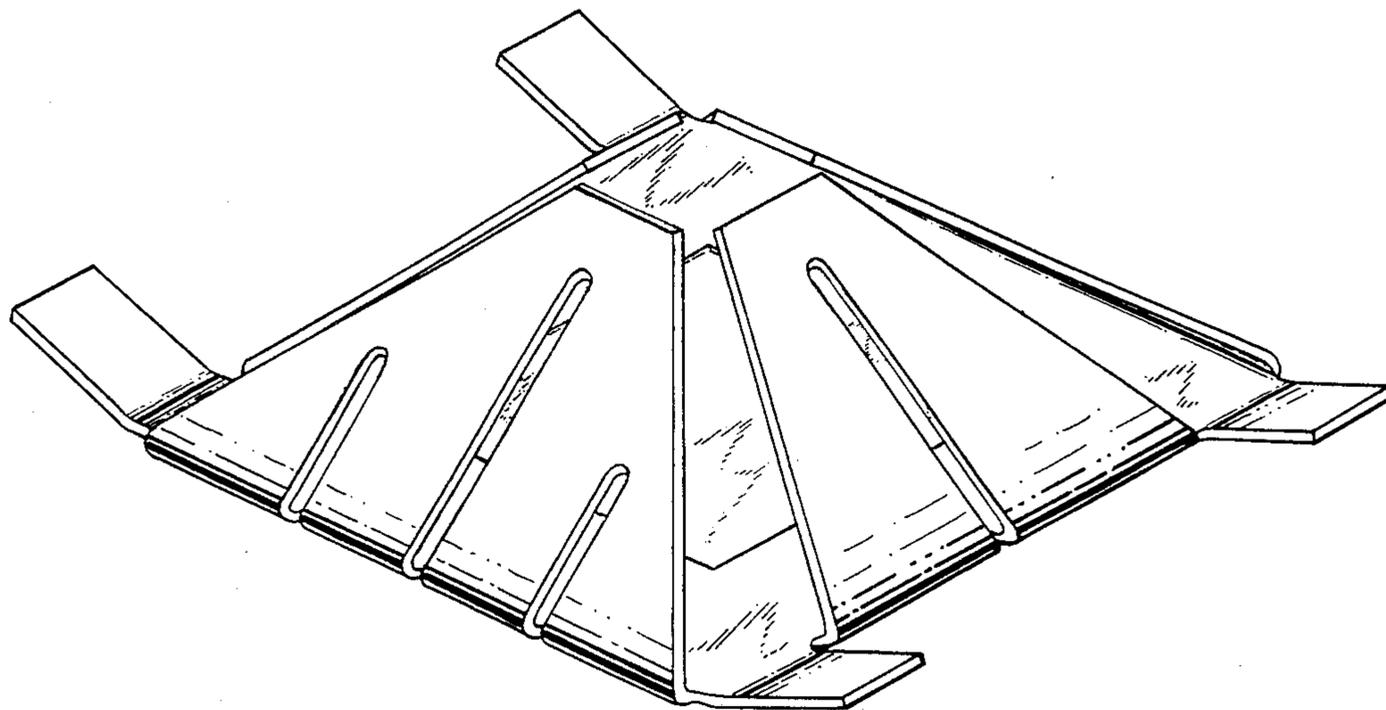


FIG. 1

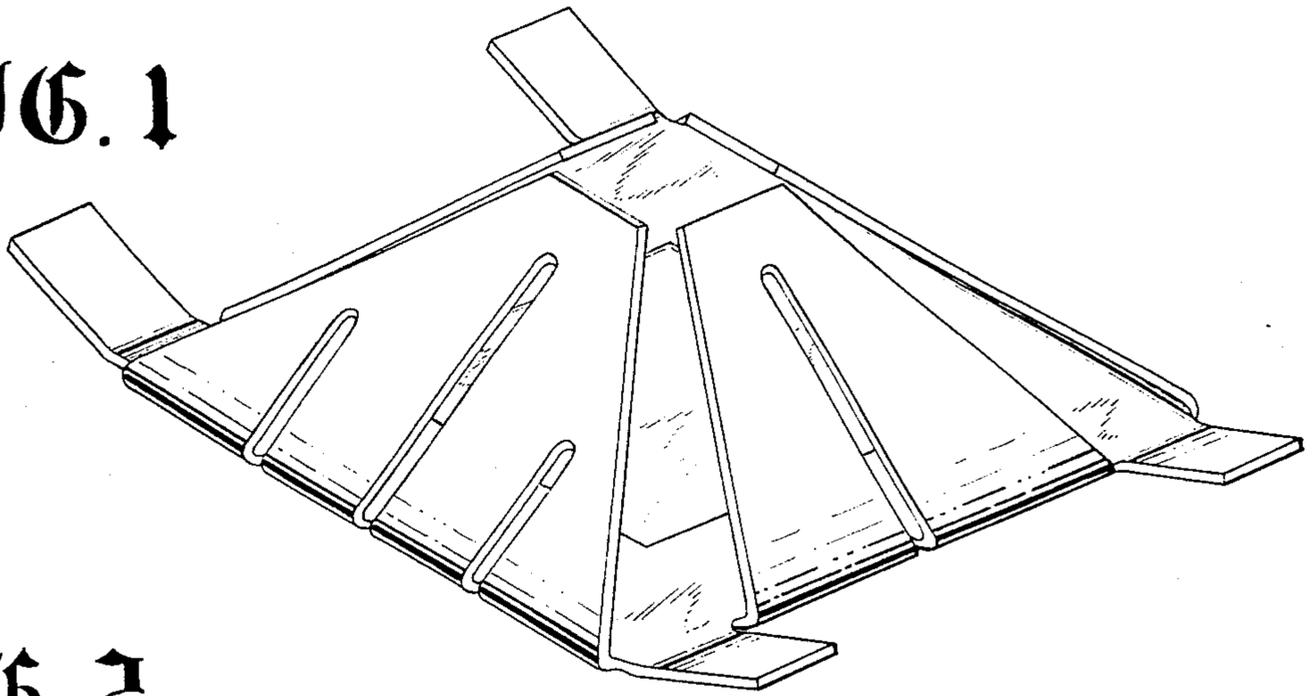


FIG. 2

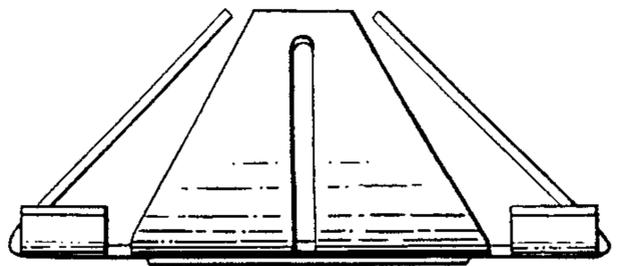
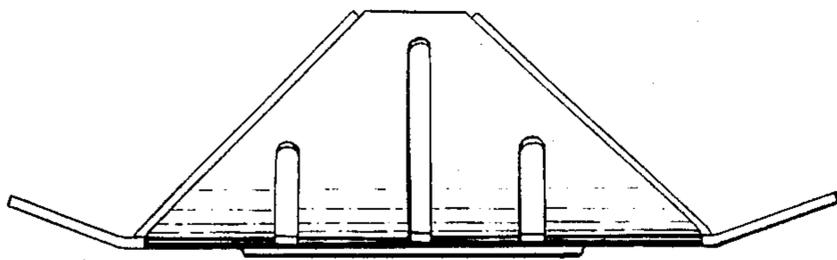


FIG. 3

FIG. 4

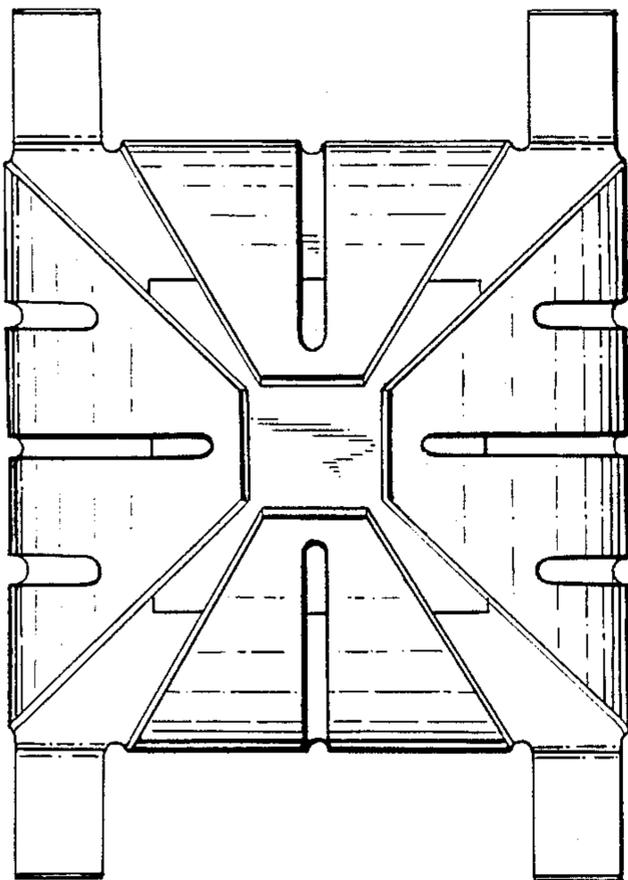


FIG. 5

